

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	0	((carrier substrate pcb ((circuit wiring) near1 board)) with (ic (integrated adj circuit) chip die (semiconductor near1 (device element))) with (bump ball (solder adj connector)) with ((compress\$4 near1 (film layer material)) rubber foam) with ((insulat\$3 dielectric) near (material underfill layer))).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/13 10:03
L2	3	((carrier substrate pcb ((circuit wiring) near1 board)) same (ic (integrated adj circuit) chip die (semiconductor near1 (device element))) same (bump ball (solder adj connector)) same ((compress\$4 near1 (film layer material)) rubber foam) same ((insulat\$3 dielectric) near (material underfill layer))).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/13 09:46
L3	36	((carrier substrate pcb ((circuit wiring) near1 board)) and (ic (integrated adj circuit) chip die (semiconductor near1 (device element))) and (bump ball (solder adj connector)) and ((compress\$4 near1 (film layer material)) rubber foam) and ((insulat\$3 dielectric) near (material underfill layer))).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/13 10:14
L4	9146	257/738,778-780,e23.021,e23.023. ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/13 10:02
L5	5638	438/108,612-613.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/13 10:02
L6	13210	4 5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/13 10:02

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L7	9349	6 and (carrier substrate pcb ((circuit wiring) near1 board)) and (ic (integrated adj circuit) chip die (semiconductor near1 (device element))) and (bump ball (solder adj connector))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/13 10:10
L8	2827	7 and ((compress\$4 near1 (film layer material)) rubber foam (underfill\$2 (under adj fill\$2)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/13 10:13
L9	93	8 and (((compress\$4 near1 (film layer material)) rubber foam (underfill\$2 (under adj fill\$2))) with surround\$3 with (bump ball (solder adj connector)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/13 10:16
L10	1	("6535237").URPN.	USPAT	OR	ON	2007/09/13 10:47
L11	27	("4500895" "4550612" "4680859" "4695853" "4862197" "5016023" "5070410" "5133495" "5203075" "5227812" "5278584" "5279711" "5323084" "5369880" "5433995" "5439956" "5442384" "5453581" "5539153" "5543585" "5545465" "5583747" "5777576" "6017117" "6113216" "6135586" "6228681").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/09/13 10:47